



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL21C040CBANNND

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 4pF, 50V, ±0.25pF, C0G, 0805

A. Samsung Part Number

<u>CL</u> <u>21</u> <u>C</u> <u>040</u> <u>C</u> <u>B</u> <u>A</u> <u>N</u> <u>N</u> <u>N</u> <u>D</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor							
2	Size	0805 (inch c	code) L: 2.0	± 0.1	mm	W:	1.25	± 0.1	mm
							.		
3	Dielectric	C0G	(8)	Inner electrode			Ni		
4	Capacitance	4 pF		Termina	ation		Cu		
(5)	Capacitance	±0.25 pF		Plating			Sn 100)%	(Pb Free)
	tolerance		9	Product	t		Norma	ıl	
6	Rated Voltage	50 V	10	Special			Reserved for future use		future use
7	Thickness	0.65 ± 0.1	mm ①	Packaging			Cardboard Type, 13" reel		ype, 13" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms					
Q	480 min						
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	300% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	COG						
Characterisitcs	(From -55 ℃ to 125 ℃, Capacitance change shoud be within ±30PPM/℃)						
Adhesive Strength	No peeling shall be occur on the	500g⋅F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change :	Bending to the limit (1mm)					
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5°C, 3±0.3sec.					
		(preheating : 80~120℃ for 10~30sec.)					
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	within ±2.5% or ±0.25pF whichever is larger						
	Tan δ, IR : initial spec.						

	Performance	Test condition					
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)					
	Tan δ, IR : initial spec.	2hours \times 3 direction (x, y, z)					
Moisture	Capacitance change :	With rated voltage					
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs					
	Q: 113.33 min						
	IR : 500Mohm or 25Mohm $\cdot \mu$ F						
	Whichever is Smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature					
	Q: 240 min	1000+48/-0hrs					
	IR : 1000Mohm or 50Mohm $\cdot \mu$ F						
	Whichever is Smaller						
Temperature	Capacitance change :	1 cycle condition					
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperatur(→ 25 °C					
	Tan δ, IR : initial spec.	$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}\!$					
		5 cycle test					

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C , 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.